
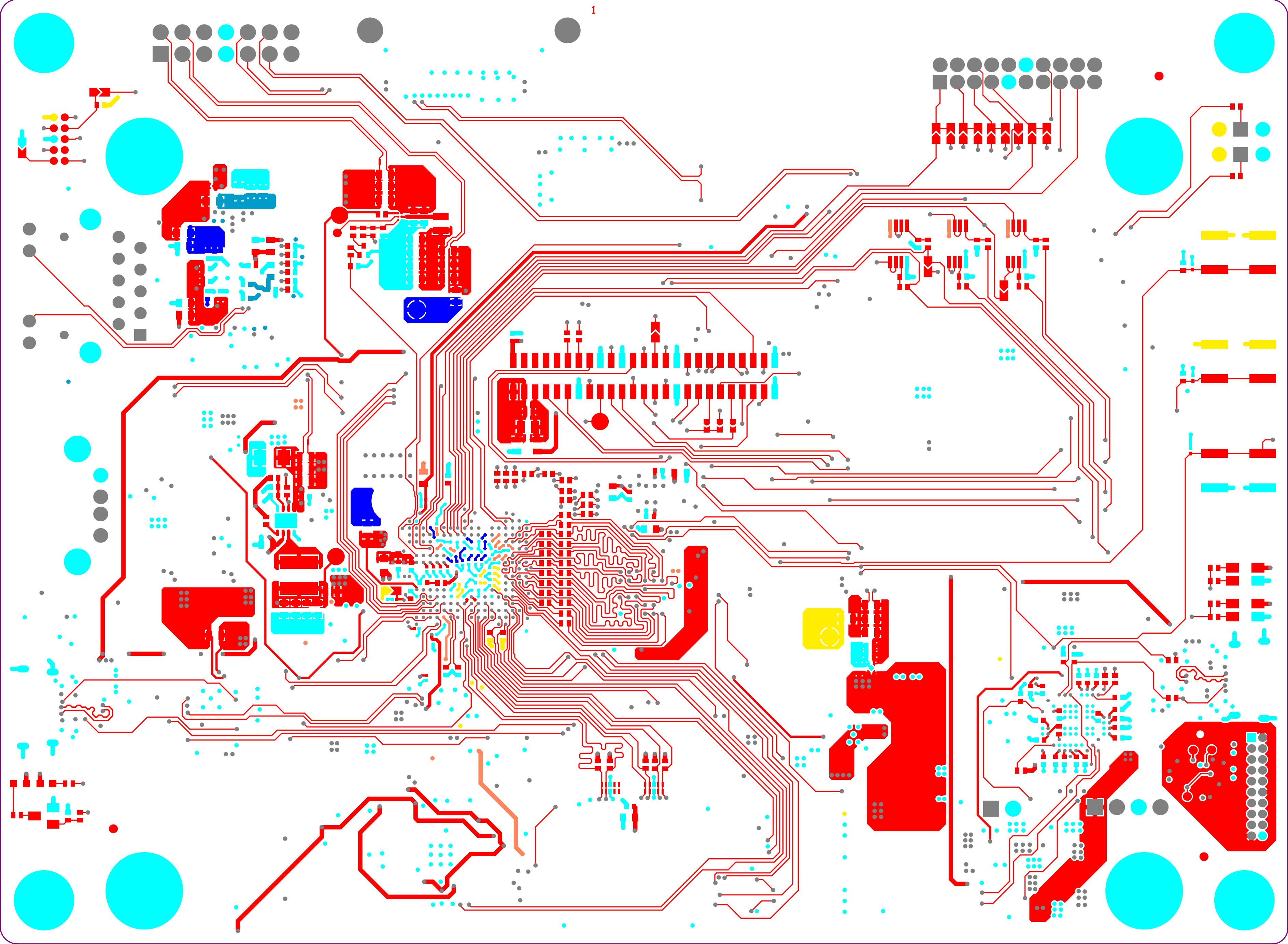

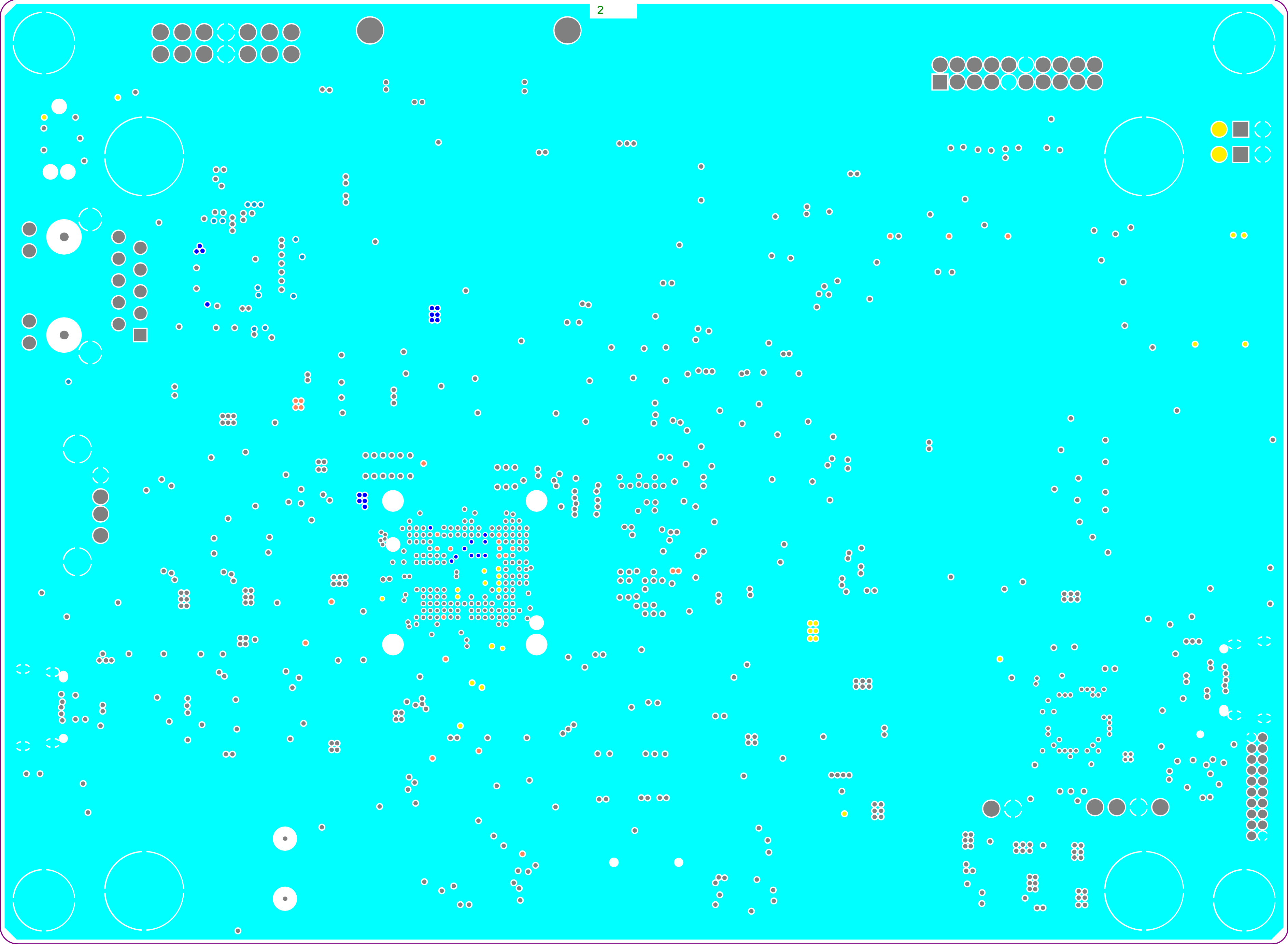



Project: STM32N6570-DK		
Layer: <b>Top Solder</b>	Gerber: <b>.GTS</b>	
Variant: [No Variations]	Ref: MB1939	
Date: 10-MAY-24	Rev: C	



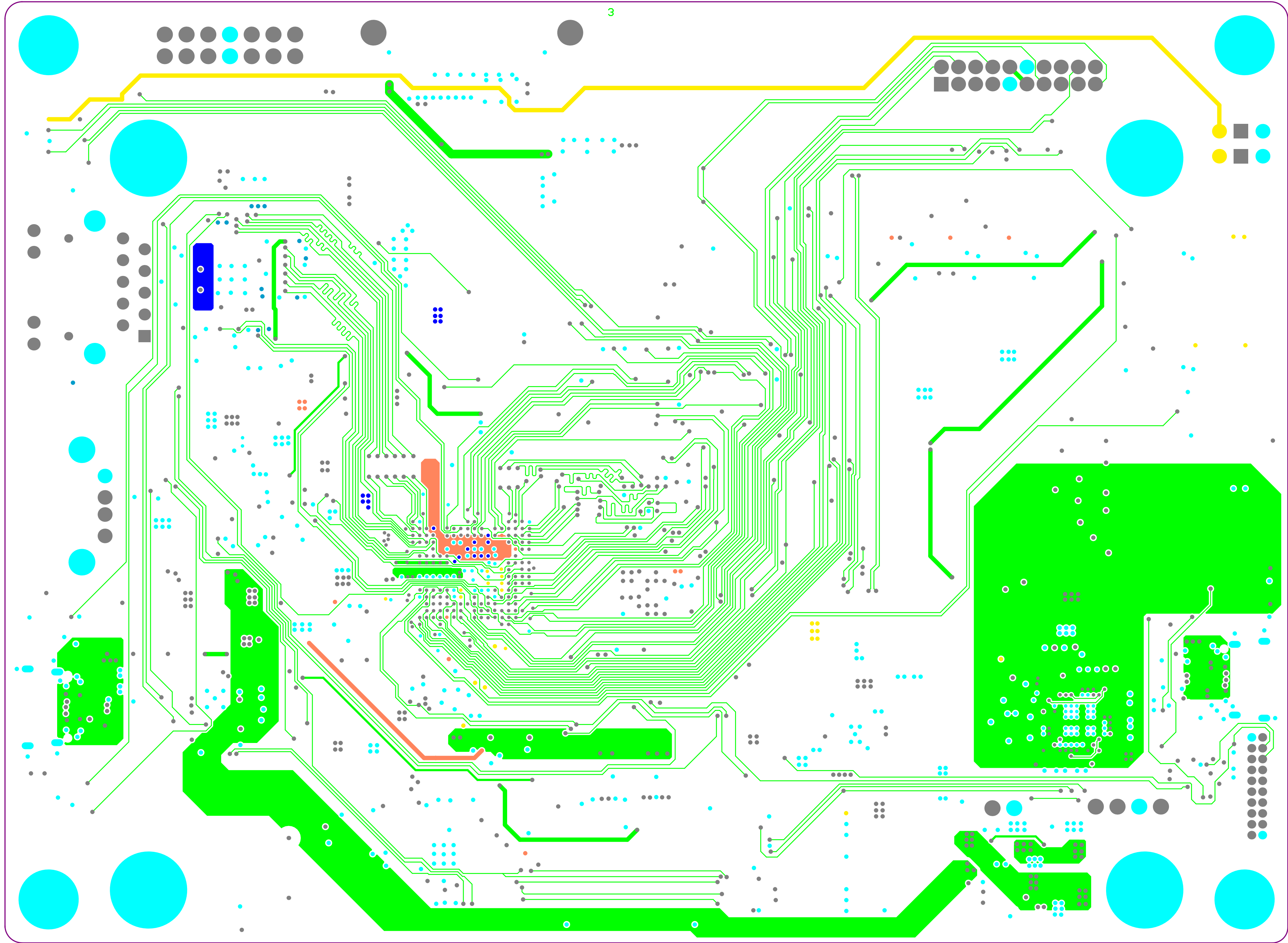
Project: STM32N6570-DK		
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: [No Variations]	Ref: MB1939	
Date: 10-MAY-24	Rev: C	




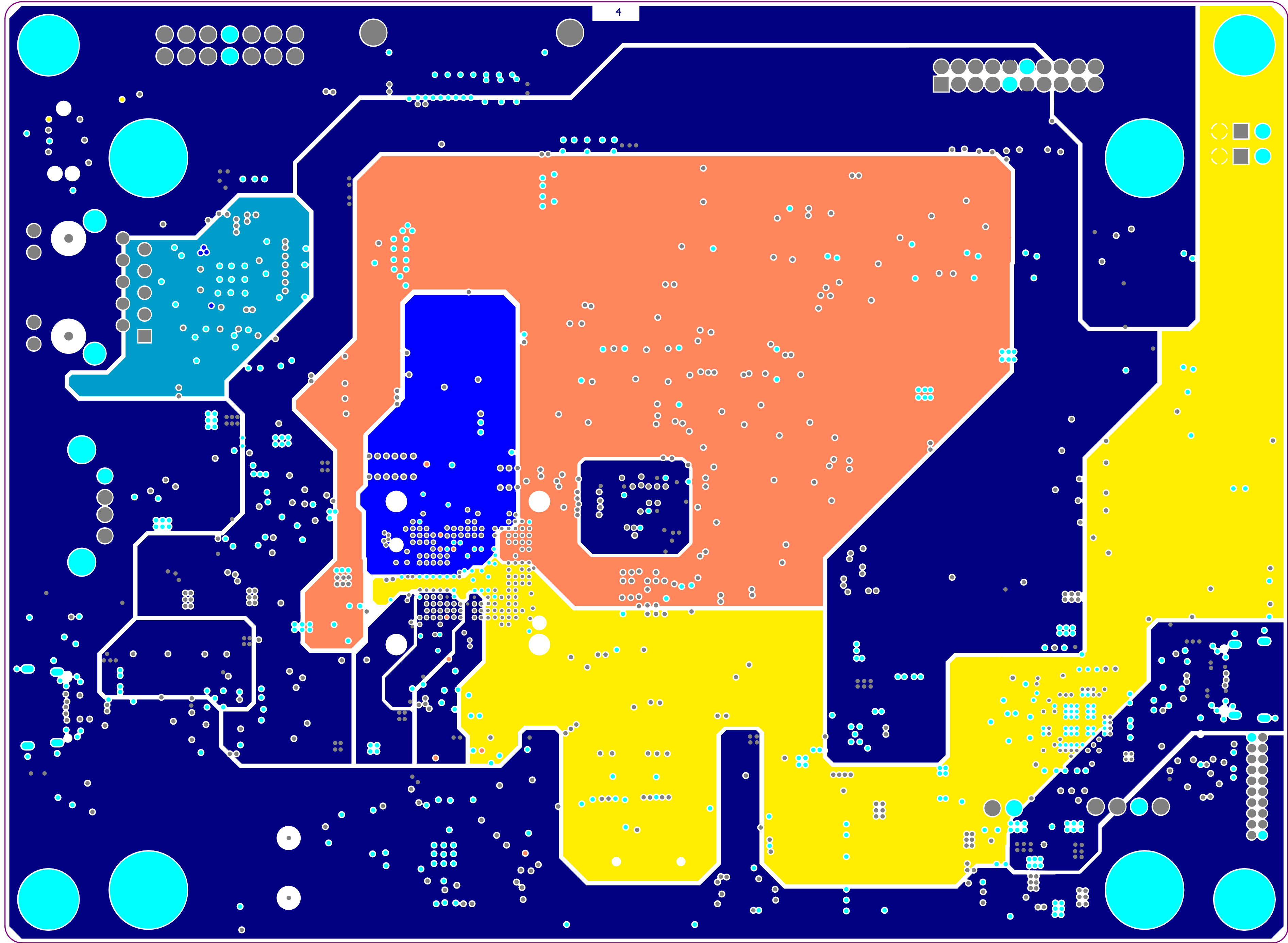



Project: STM32N6570-DK		
Layer: I2_GND	Gerber: .G1	
Variant: [No Variations]	Ref: MB1939	
Date: 10-MAY-24	Rev: C	



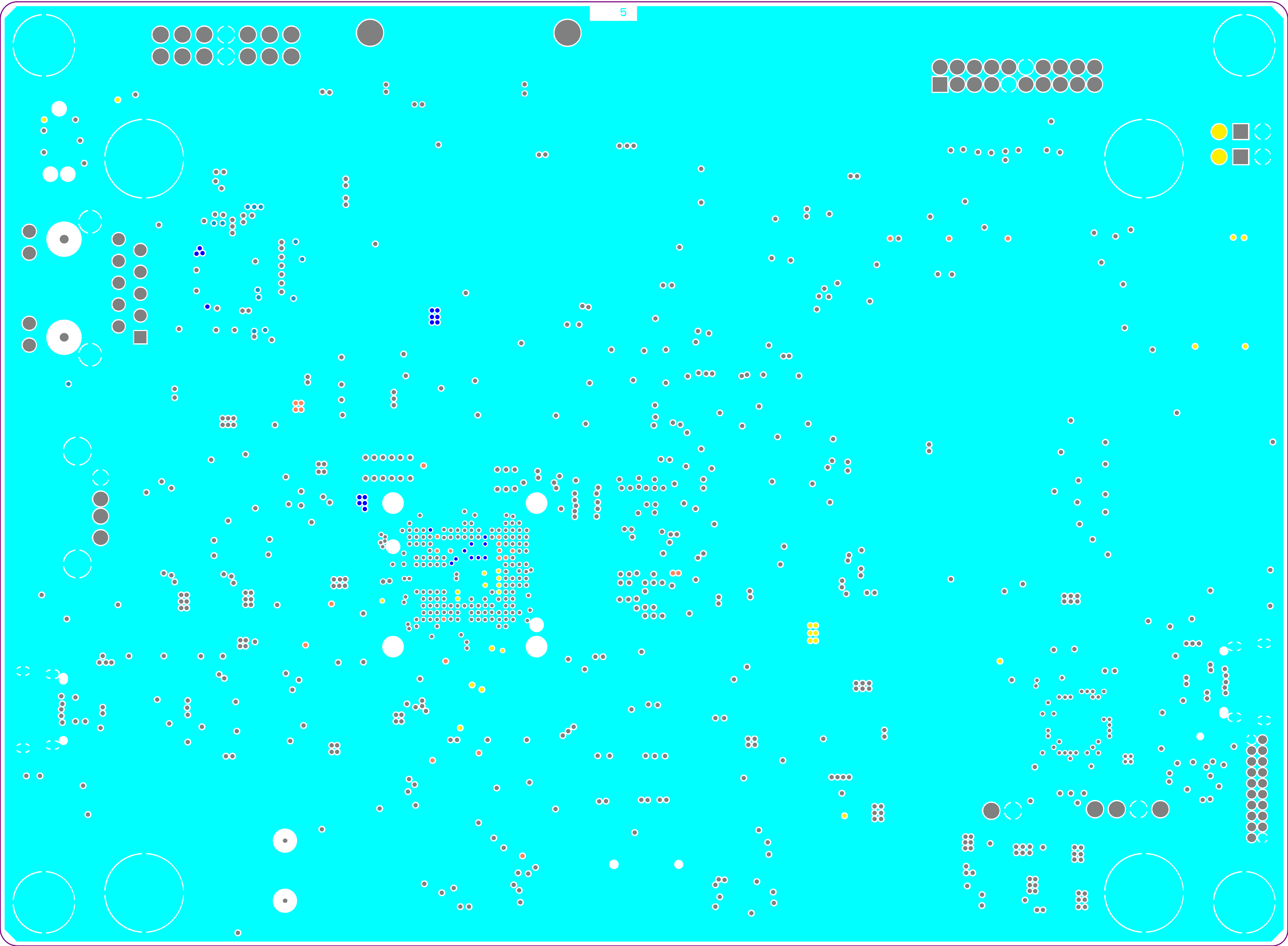



Project: STM32N6570-DK		
Layer: L3_SIG	Gerber: .G2	
Variant: [No Variations]	Ref: MB1939	
Date: 10-MAY-24	Rev: C	



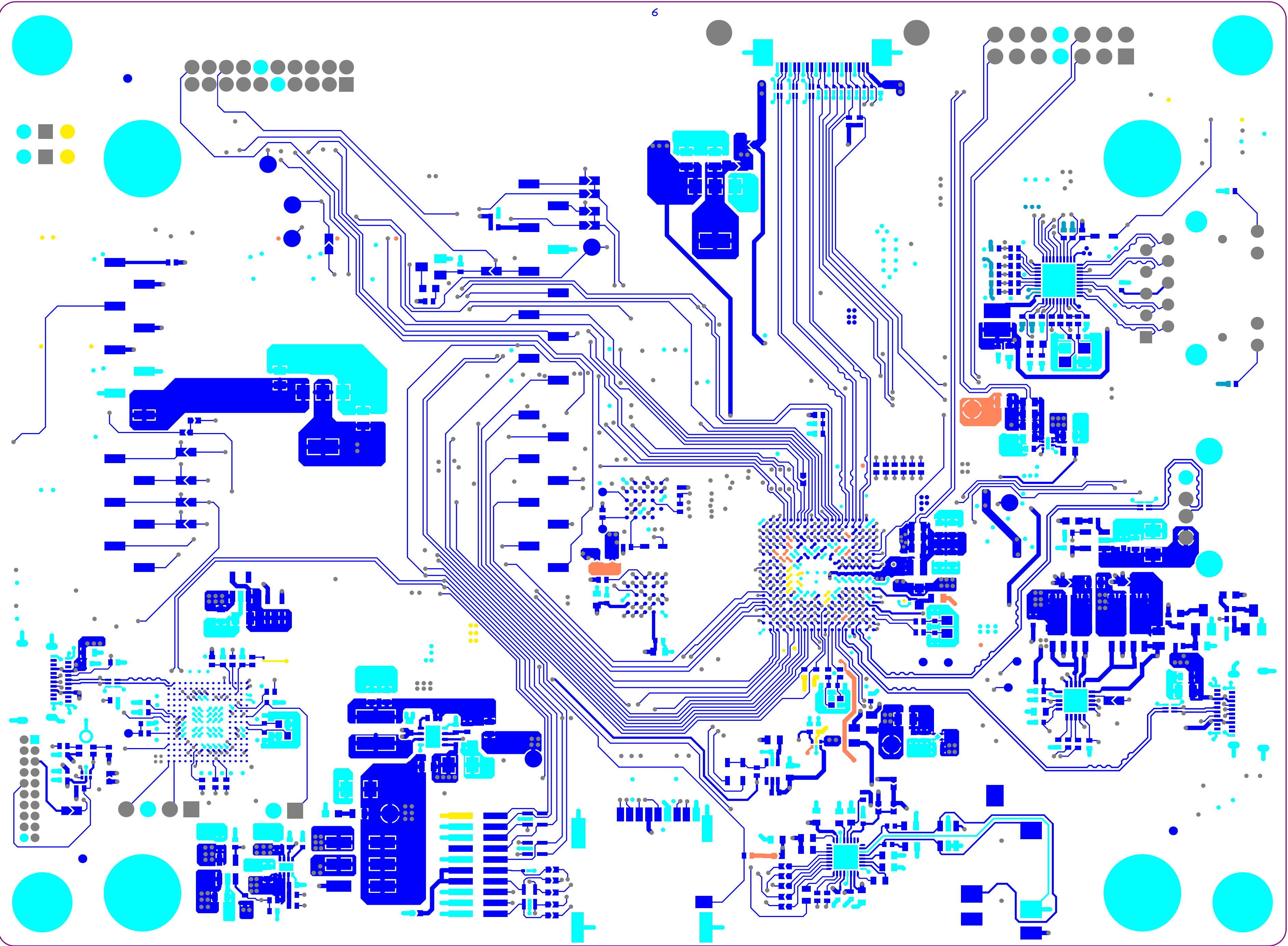
Project: STM32N6570-DK		
Layer: L4_VCC	Gerber: .G3	
Variant: [No Variations]	Ref: MB1939	
Date: 10-MAY-24	Rev: C	





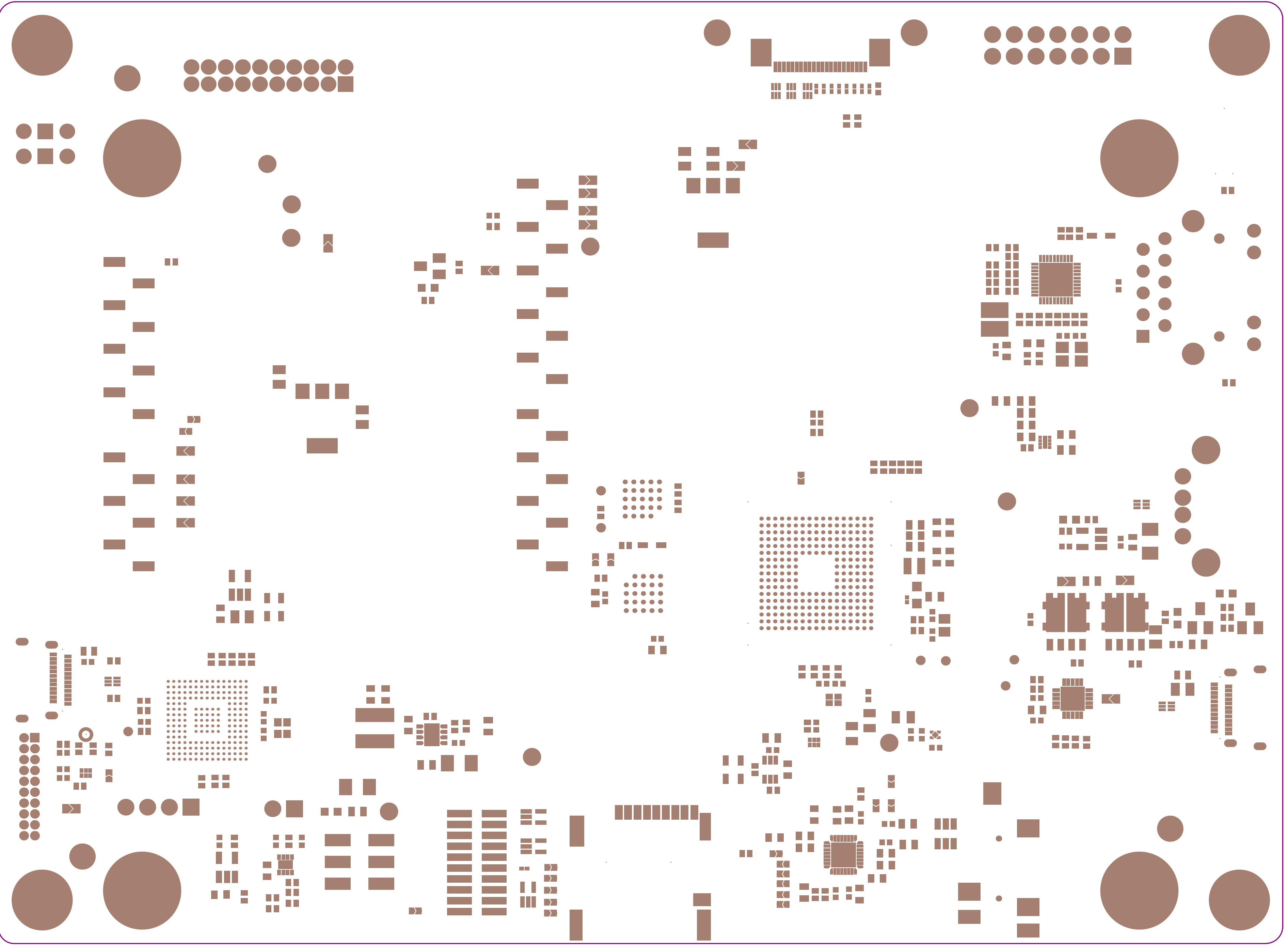
Project: STM32N6570-DK		
Layer: L5_GND	Gerber: .G4	
Variant: [No Variations]	Ref: MB1939	
Date: 10-MAY-24	Rev: C	





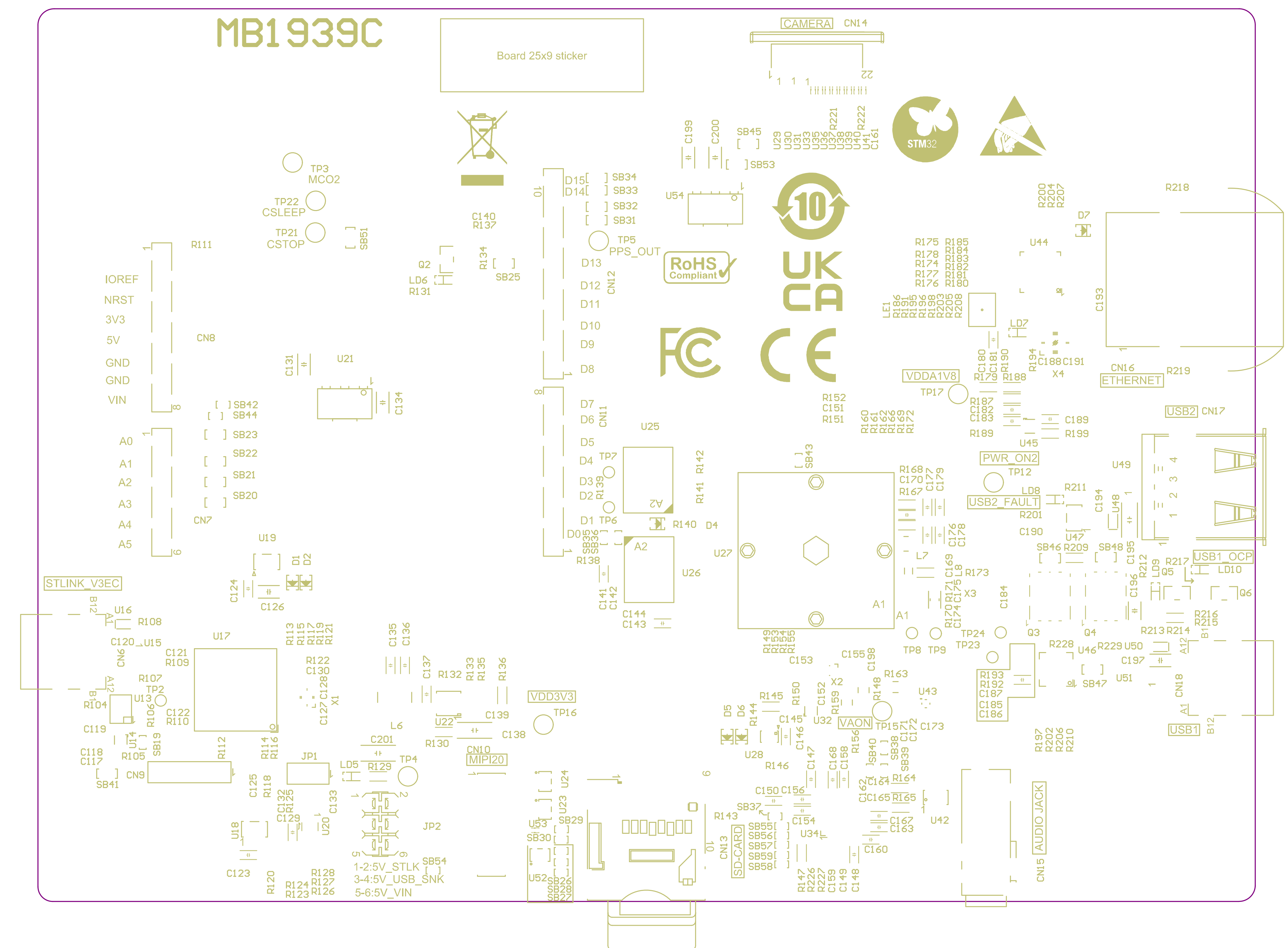
Project: STM32N6570-DK	
Layer: Bottom Layer	Gerber: .GBL
Variant: [No Variations]	Ref: MB1939
Date: 10-MAY-24	Rev: C





Project: STM32N6570-DK	
Layer: Bottom Solder	Gerber:.GBS
Variant: [No Variations]	Ref: MB1939
Date: 10-MAY-24	Rev: C





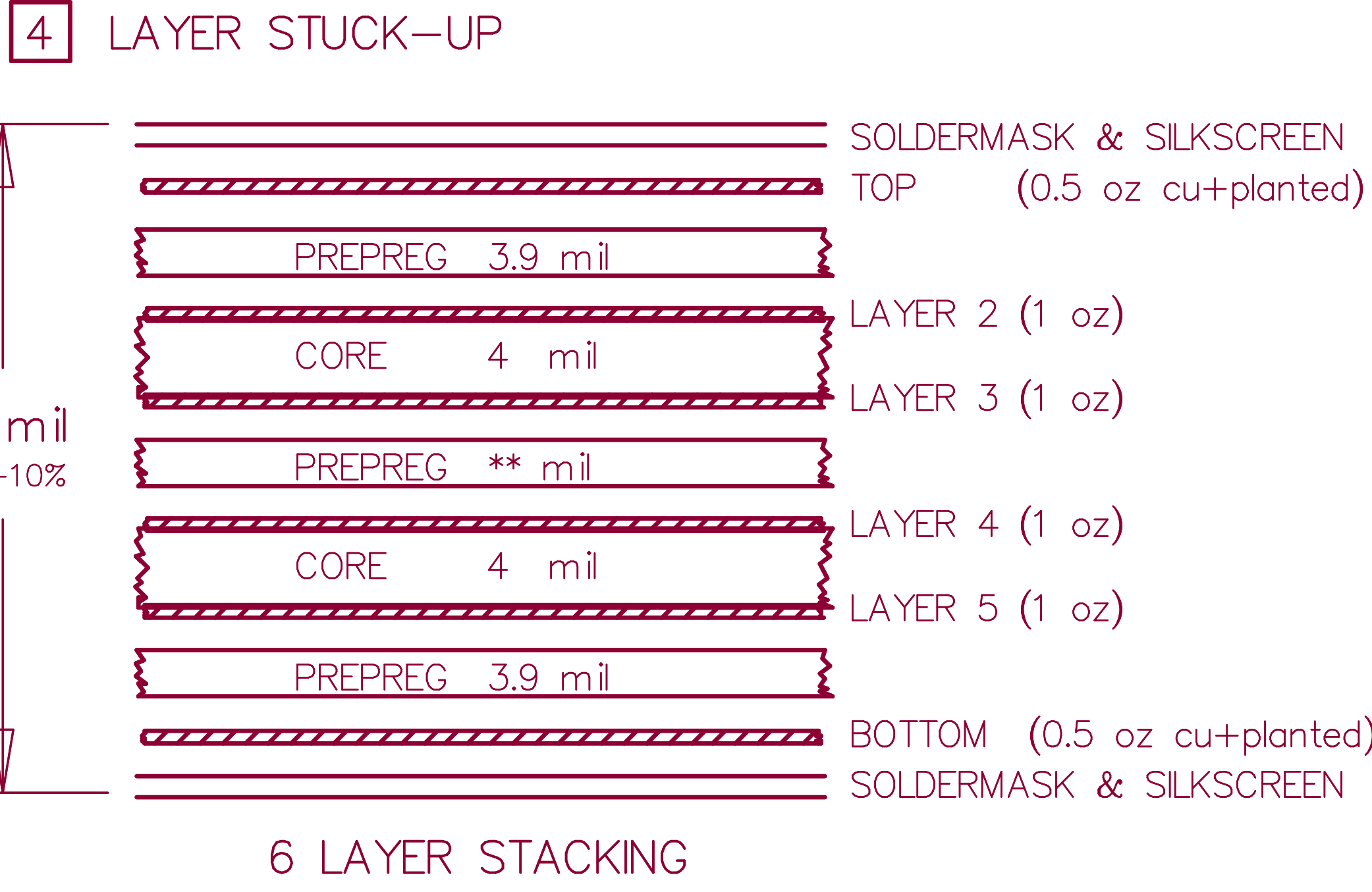
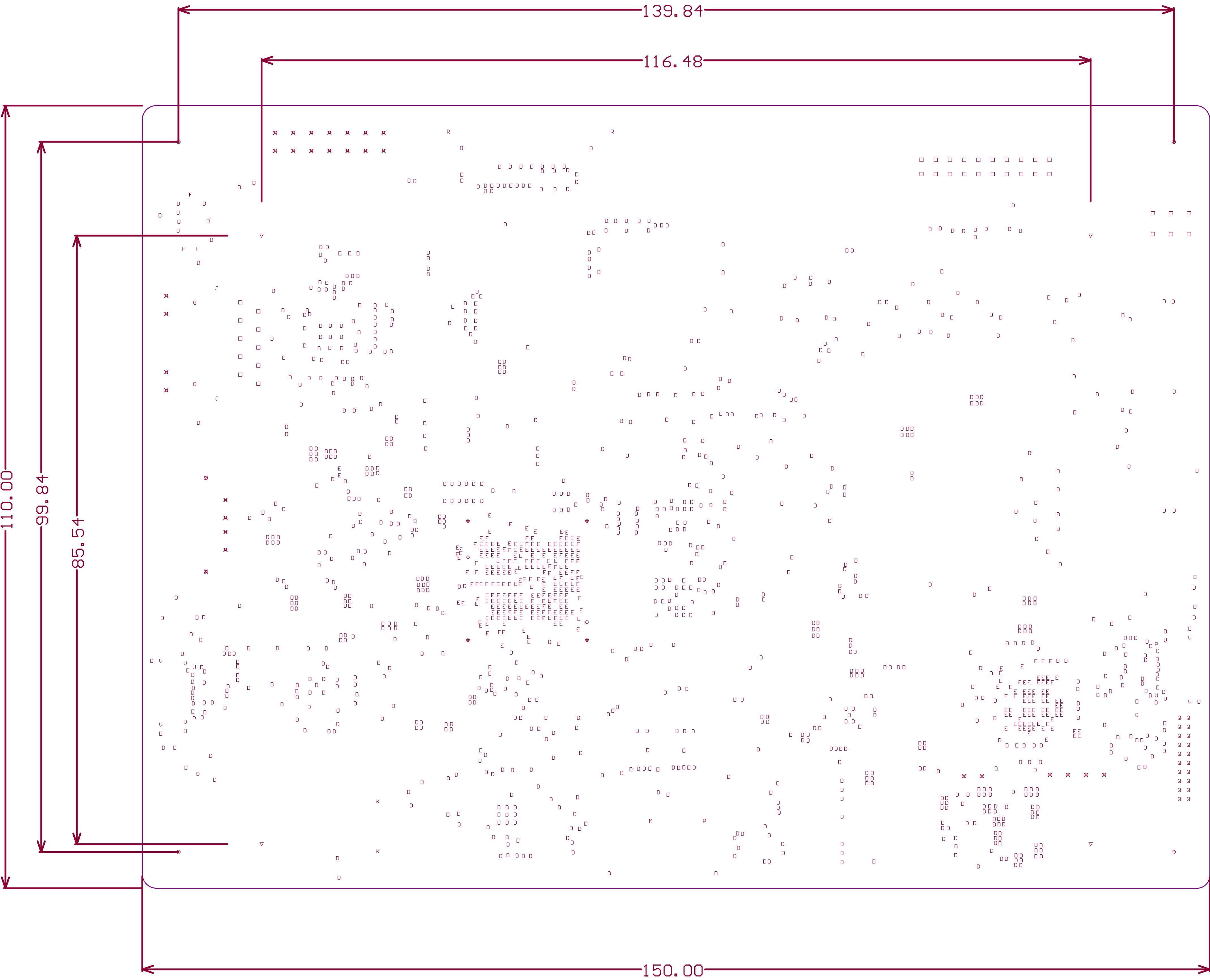
Project: STM32N6570-DK	
Layer: Bottom Overlay	Gerber: .GBO
Variant: [No Variations]	Ref: MB1939
Date: 10-MAY-24	Rev: C





5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,6 3	5.0 4.0	N/A	55 OHM	N/A	+/-10%
1,6	6.1	8.9	N/A	90 OHM	+/-10%
6	5.1	9.9	N/A	100 OHM	+/-10%



PCB SPECIFICATIONS :

- A. MATERIAL : FR-4 ☐TG-170 ☒TG-150 ☐TG-140
- B. MATERIAL FAMILY : N/A
- C. SOLDERMASK COLOR : ☐GREEN ☐WHITE ☐RED ☐BLACK ☒Blue ink PANTONE 2955
- D. SILKSCREEN COLOR : ☒WHITE ☐YELLOW ☐BLACK ☐Blue ink PANTONE 2955
- E. SURFACE FINISH : ☒ENIG ☐IMMERSION SILVER ☐IMMERSION TIN
- ☐HASL ☐HASL (PB-FREE) ☐GOLDEN FINGER
- F. IMPEDANCE CONTROL : ☐NO ☒YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA : PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
- H. STACK-UP : PLUG MATERIAL : ☒SOLDERMASK ☐NON-CONDUCTIVE EPOXY.  
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3


ASPECT-RATIO, AXE Z :  
6:1 to 8:1  
LEVEL  
"B"

MINIMUM PARAMETERS

DEFAULT  
TRACKS : 0.127mm  
GAPS : 0.1274mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
C	1	19.69mil <0.500mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn50m5			
M	1	27.56mil <0.700mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn70m5			
U	2	25.59mil <0.650mm>	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn65_95m5			
◇	2	33.47mil <0.850mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn85m5			
J	2	66.93mil <1.700mm>	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c250h170m255			
K	2	78.74mil <2.000mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c50hn200m60			
R	2	86.61mil <2.200mm>	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c300h220m305p254297			
⊗	2	94.49mil <2.400mm>	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c310h240m320			
G	2	125.98mil <3.200mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c100hn320m110			
P	3	25.59mil <0.650mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn65m5			
F	3	43.31mil <1.100mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn110m5			
✱	4	63.39mil <1.610mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn161m5			
⊕	4	137.80mil <3.500mm>	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c700h350m705			
▽	4	177.17mil <4.500mm>	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c900h450m905			
U	8	19.69mil <0.500mm>	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r140_80h50_110r100m145_85			
Q	20	27.56mil <0.700mm>	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	<Mixed>			
✕	28	39.37mil <1.000mm>	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	<Mixed>			
□	36	35.43mil <0.900mm>	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>			
E	316	8.00mil <0.203mm>	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v41h20m0mx0			
D	1072	10.00mil <0.254mm>	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v51h25m0mx0			
	1514 Total										

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: STM32N6570-DK		
Layer: <b>Drill Drawing</b>	Gerber: <b>.DRL</b>	
Variant: [No Variations]	Ref: MB1939	
Date: 10-MAY-24	Rev: C	